

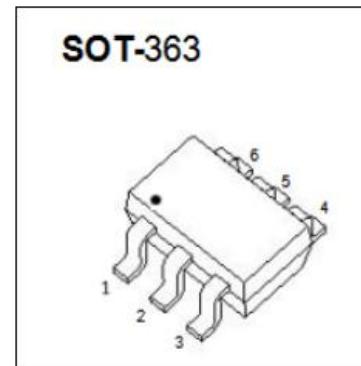
Plastic-Encapsulate MOSFETs

N-Channel and P-Channel Silicon MOSFETs

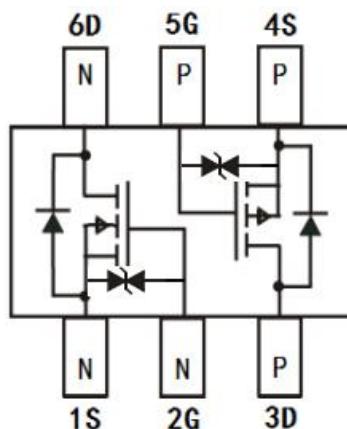
Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Lead Free By Design/RoHS Compliant (Note 2)
- ESD Protected up to 2kV

MARKING:P2N



Equivalent Circuit



Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	20	V
Gate-Source Voltage			V_{GSS}	± 6	V
Continuous Drain Current (Note 1)	Steady State	$T_A = 25^\circ\text{C}$ $T_A = 85^\circ\text{C}$	I_D	0.63 0.45	A
Pulsed Drain Current			I_{DM}	6	A

Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 1)		P_D	0.28	W
Thermal Resistance, Junction to Ambient		$R_{\theta JA}$	452	°C/W
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Notes:

1. Device mounted on FR-4 PCB.
2. No purposefully added lead.

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic		Symbol	Value	Units
Drain-Source Voltage		V_{DSS}	-20	V
Gate-Source Voltage		V_{GSS}	± 6	V
Drain Current (Note 1) Steady State	$T_A = 25^\circ\text{C}$	I_D	-0.46	A
	$T_A = 85^\circ\text{C}$		-0.33	
Pulsed Drain Current		I_{DM}	-6	A

Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 1)	P_D	0.27	W
Thermal Resistance, Junction to Ambient	R_{JA}	461	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Notes:
 1. Device mounted on FR-4 PCB.
 2. No purposefully added lead.

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified - N-channel

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 4)						
Drain-Source Breakdown Voltage	BV_{DSS}	20	-	-	V	$V_{GS} = 0V, I_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current $T_J = 25^\circ\text{C}$	$I_{DS(0)}$	-	-	100	nA	$V_{DS} = 20V, V_{GS} = 0V$
Gate-Source Leakage	I_{GSS}	-	-	± 1.0	μA	$V_{GS} = \pm 4.5V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 4)						
Gate Threshold Voltage	$V_{GS(on)}$	0.5	-	1.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(on)}$	-	0.3	0.4	Ω	$V_{GS} = 4.5V, I_D = 600\text{mA}$
			0.4	0.5		$V_{GS} = 2.5V, I_D = 500\text{mA}$
			0.5	0.7		$V_{GS} = 1.8V, I_D = 350\text{mA}$
Forward Transfer Admittance	$ Y_{FS} $	-	1.4	-	S	$V_{DS} = 10V, I_D = 400\text{mA}$
Diode Forward Voltage (Note 4)	V_{SD}		0.7	1.2	V	$V_{GS} = 0V, I_S = 150\text{mA}$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{iss}	-	60.67	-	pF	$V_{DS} = 16V, V_{GS} = 0V, f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	-	9.68	-	pF	
Reverse Transfer Capacitance	C_{rss}	-	5.37	-	pF	
Total Gate Charge	Q_g	-	736.6	-	pC	$V_{GS} = 4.5V, V_{DS} = 10V, I_D = 250\text{mA}$
Gate-Source Charge	Q_{gs}	-	93.6	-	pC	
Gate-Drain Charge	Q_{gd}	-	116.6	-	pC	
Turn-On Delay Time	$t_{D(on)}$	-	5.1	-	ns	$V_{DD} = 10V, V_{GS} = 4.5V, R_L = 47\Omega, R_G = 10\Omega, I_D = 200\text{mA}$
Turn-On Rise Time	t_r	-	7.4	-	ns	
Turn-Off Delay Time	$t_{D(off)}$	-	26.7	-	ns	
Turn-Off Fall Time	t_f	-	12.3	-	ns	

Notes: 4. Short duration pulse test used to minimize self-heating effect.

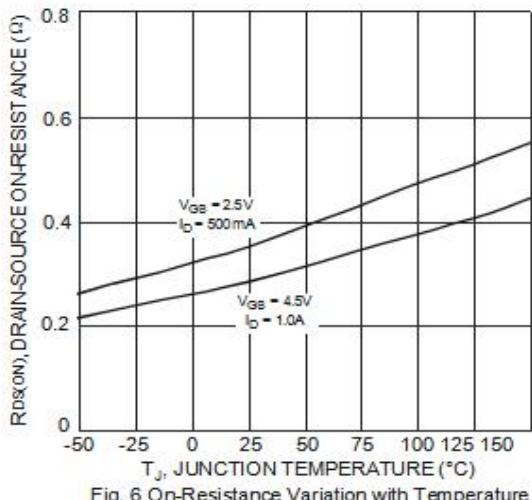
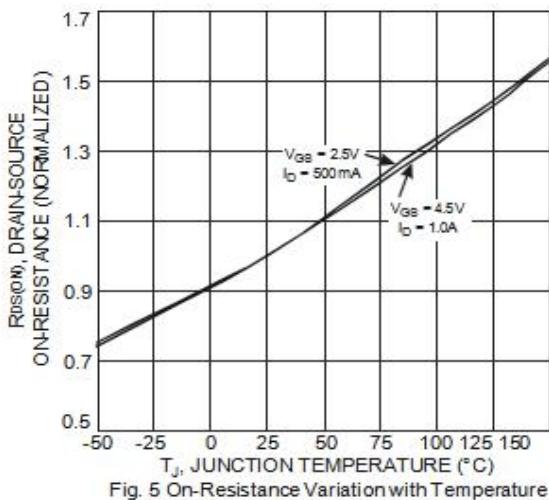
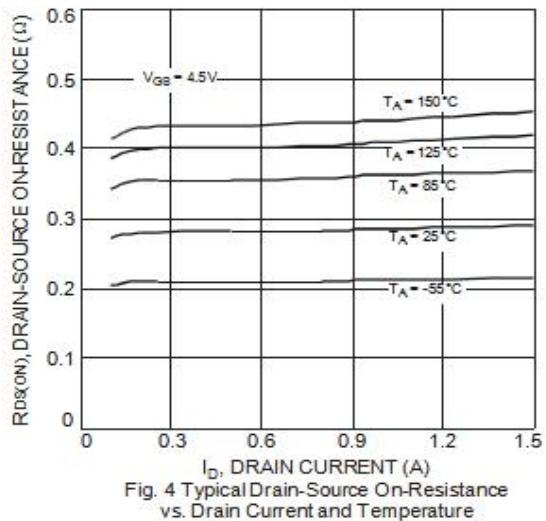
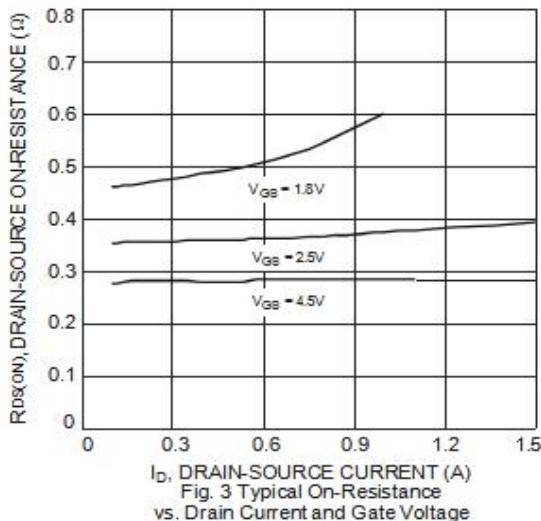
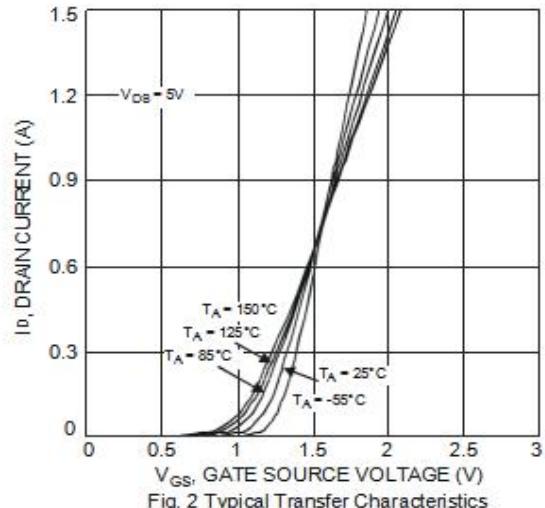
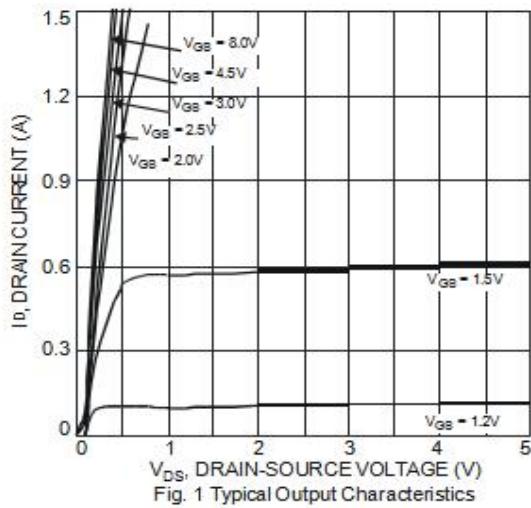
Electrical Characteristics @ $T_A = 25^\circ C$ unless otherwise specified - P-channel

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 4)						
Drain-Source Breakdown Voltage	BV_{DSS}	-20	-	-	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current $T_J = 25^\circ C$	$I_{DS(0)}$	-	-	-100	nA	$V_{DS} = -20V, V_{GS} = 0V$
Gate-Source Leakage	I_{GS}	-	-	± 2.0	μA	$V_{GS} = \pm 4.5V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 4)						
Gate Threshold Voltage	$V_{GS(on)}$	-0.5	-	-1.0	V	$V_{DS} = V_{GS}, I_D = -250\mu A$
Static Drain-Source On-Resistance	$R_{DS(on)}$	-	0.5	0.7	Ω	$V_{GS} = -4.5V, I_D = -350mA$
			0.7	0.9		$V_{GS} = -2.5V, I_D = -300mA$
			1.0	1.3		$V_{GS} = -1.8V, I_D = -150mA$
Forward Transfer Admittance	$ Y_{fs} $	-	0.9	-	S	$V_{DS} = -10V, I_D = -250mA$
Diode Forward Voltage (Note 4)	V_{SD}		-0.8	-1.2	V	$V_{GS} = 0V, I_S = -150mA$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{iss}	-	59.76	-	pF	$V_{DS} = -16V, V_{GS} = 0V, f = 1.0MHz$
Output Capacitance	C_{oss}	-	12.07	-	pF	
Reverse Transfer Capacitance	C_{rss}	-	6.36	-	pF	
Total Gate Charge	Q_g	-	622.4	-	pC	$V_{GS} = -4.5V, V_{DS} = -10V, I_D = -250mA$
Gate-Source Charge	Q_{gs}	-	100.3	-	pC	
Gate-Drain Charge	Q_{gd}	-	132.2	-	pC	
Turn-On Delay Time	$t_{D(on)}$	-	5.1	-	ns	$V_{DD} = -10V, V_{GS} = -4.5V, R_L = 47\Omega, R_G = 10\Omega, I_D = -200mA$
Turn-On Rise Time	t_r	-	8.1	-	ns	
Turn-Off Delay Time	$t_{D(off)}$	-	28.4	-	ns	
Turn-Off Fall Time	t_f	-	20.7	-	ns	

Notes: 4. Short duration pulse test used to minimize self-heating effect.

Typical Characteristics

N-channel



Typical Characteristics

P-channel

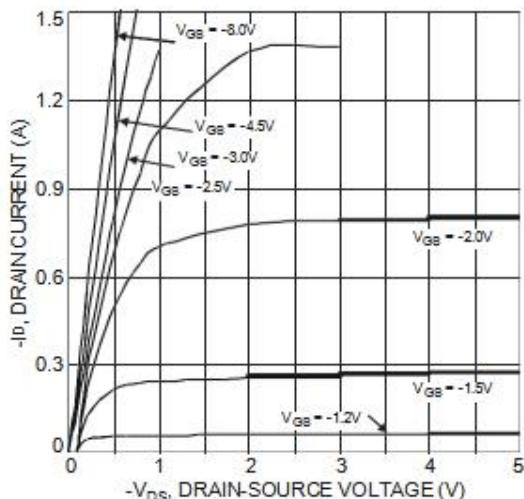


Fig. 1 Typical Output Characteristic

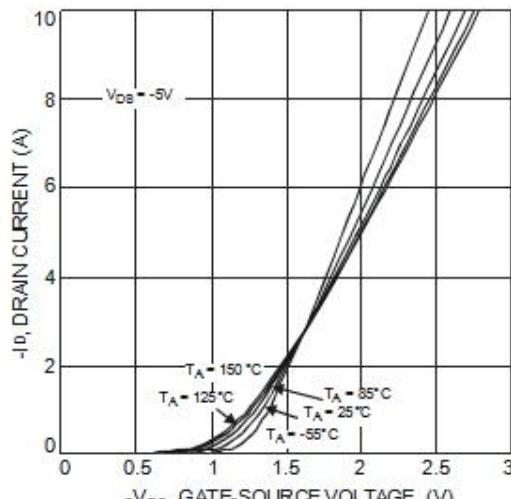


Fig. 2 Typical Transfer Characteristic

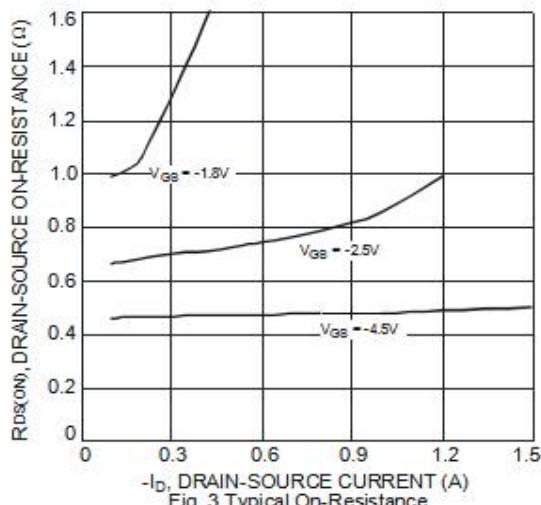


Fig. 3 Typical On-Resistance
vs. Drain Current and Gate Voltage

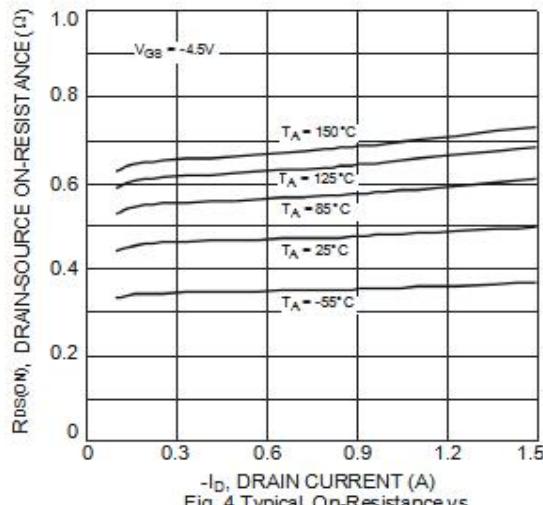


Fig. 4 Typical On-Resistance vs.
Drain Current and Temperature

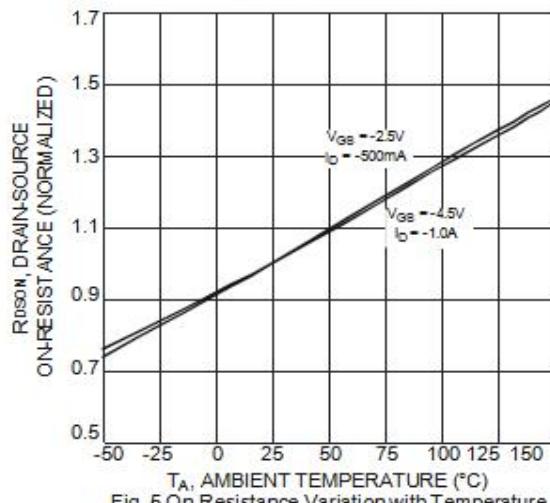


Fig. 5 On-Resistance Variation with Temperature

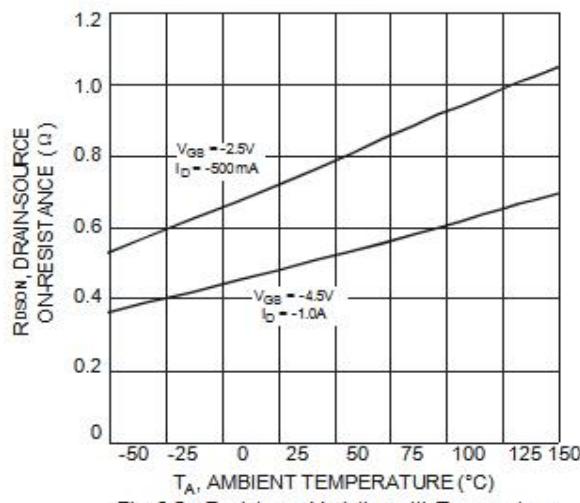
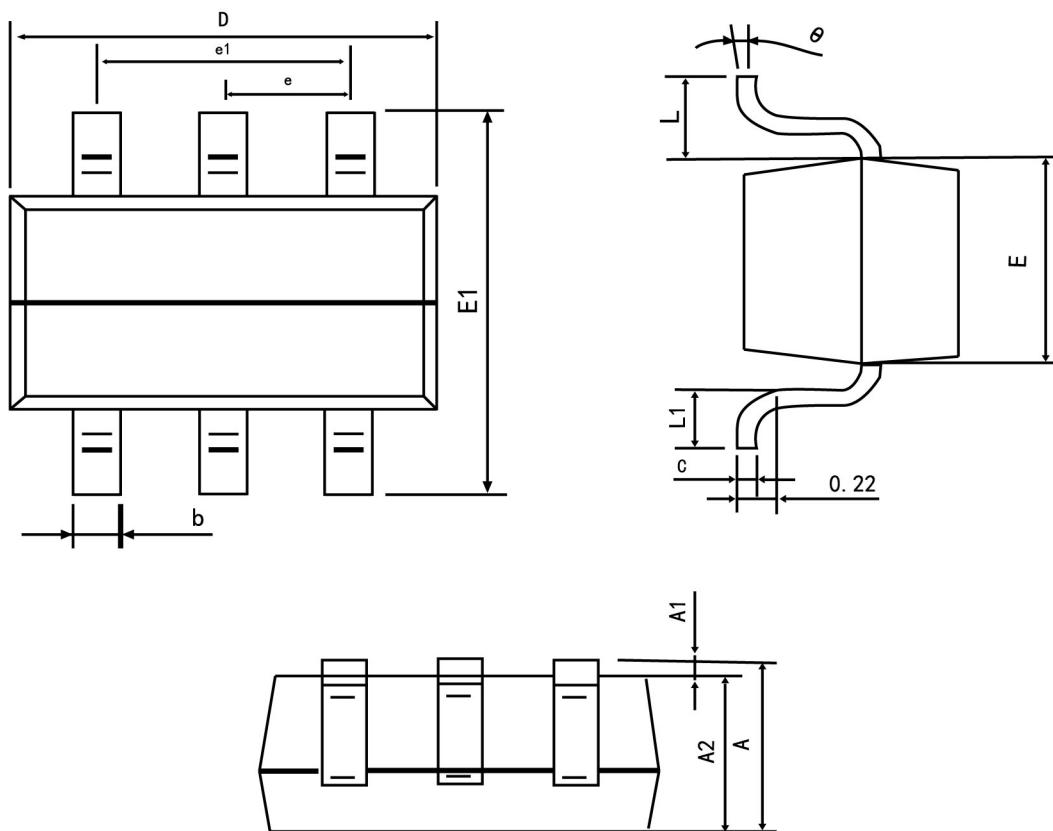


Fig. 6 On-Resistance Variation with Temperature

SOT-363-Package Outline Dimensions


Symbol	Dimension in Millimeters	
	Min	Max
A	0.900	1.100
A1	0.000	0.100
A2	0.900	1.000
b	0.150	0.350
c	0.080	0.150
D	2.000	2.200
E	1.150	1.350
E1	2.150	2.450
e	0.650 TYP	
e1	1.200	1.400
L	0.525 REF	
L1	0.260	0.460
θ	0°	8°